

IN THE CLAIMS:

Kindly replace claims 1-14, as follows.

1. (Amended) A method for manufacturing a device with an integrated circuit chip with at least one active surface provided with at least one connection pad and an opposite face, said method comprising the steps of:

initially providing a thin active circuit which has mechanical flexibility;
affixing the thin active circuit to a stiffening substrate via its opposite face to form an assembly composed of the thin active circuit and the stiffening substrate;

forming in the general plane of a face of a final support a communication interface having at least one element for connection with the active circuit;

presenting this assembly, comprising the active circuit with its stiffening substrate, against the communication interface, with the connection pad against a corresponding connection element;

fixing and electrically coupling the connection pad with a corresponding connection element; and

removing the stiffening substrate from the opposite face.

2. (Amended) A method according to Claim 1, wherein the communication interface comprises at least one of an ohmic contact area and antenna area protruding on a portion of a surface in the general plane of the face of the final support.

3. (Amended) A method according to Claim 1 wherein the connection pad is fixed and coupled with its respective connection element by welding by means of a laser beam which passes through the stiffening substrate and the active circuit, said substrate and circuit being transparent to the wavelength used for the welding, whilst the pad and/or the connection element is fusible under the effect of said laser beam.

4. (Amended) A method according to claim 1 wherein the support for fixing the active circuit is in roll form.

5. (Amended) A method according to claim 1 further including, after the step of removing the stiffening substrate, a step of depositing, on the opposite face, a protective film by lacquer printing.

6. (Amended) A method according to claim 1 further including a step of cutting the assembly including the active circuit and the stiffening substrate into an assembly cut substantially to the dimensions of the circuit, before the step of presenting this assembly.

7. (Amended) A method according to claim 1 wherein each pad is fixed with its respective connection element by a compression force that is applied through the stiffening substrate of the assembly.

8. (Amended) A method according to Claim 6, wherein the connection pad is fixed and coupled with its respective connection element by welding by means of a laser beam which passes through the stiffening substrate and the active circuit, said substrate and circuit being transparent to the wavelengths used for the welding, whilst the pad and/or the connection element is fusible under the effect of said laser beam.

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9. (Amended) Tooling for implementing the method according to Claim 8, comprising a laser with a wavelength of $1.06 \mu\text{m}$, whose beam is transmitted by a plurality of optical paths, each directed towards a respective pad of the active circuit, in order to effect welds in parallel.

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10. (Amended) Tooling according to Claim 9, wherein each optical path is produced by at least one optical fibre.

11. (Amended) Tooling according to Claim 9 wherein the optical paths are integrated in a tool for positioning and/or holding the assembly vis-à-vis the final support.

12. (Amended) A device with an integrated-circuit chip comprising at least one active circuit with a front face provided with at least one connection pad and an opposite face, said active circuit being a thin active circuit which has mechanical flexibility, and which is mounted on said support;

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an interface in the overall plane of one face of the support for communication with
at least one element for connection with the active circuit and;

NP out said connection pad being fixed and electrically coupled against a corresponding
connection element on said interface.

13. (Amended) A device according to Claim 12, further including a protective
film over the surface of the support.

14. (Amended) A device according to Claim 12 wherein the thickness of the
connection elements and of the active circuit with its pads is less than 50 microns.

Alb
Add the following new claims:

15. (New) The method of claim 3, wherein said laser beam has a wavelength of
about $1.06\mu\text{m}$.

A7 16. (New) The method of claim 5, wherein said communication interface
comprises an ohmic contact area, and further including the step of removing the film from
said area.

17. (New) The method of claim 5, wherein said film has a thickness in the
range of $5-15\mu\text{m}$.